

MA4X746 (MA746)

Silicon epitaxial planar type

For super-high speed switching circuit
For small current rectification

■ Features

- $I_{F(AV)} = 200 \text{ mA}$, and $V_R > 50 \text{ V}$ is achieved
- Allowing automatic insertion with the emboss taping
- Optimum for high-frequency rectification because of its short reverse recovery time (t_{rr})
- High rectification efficiency caused by its low forward-rise-voltage (V_F)

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage (DC)	V_R	50	V
Repetitive peak reverse voltage	V_{RRM}	50	V
Non repetitive peak forward current*2	Single	I_{FSM}	A
	Double*1	1	
Peak forward current	Single	I_{FM}	mA
	Double*1	300	
Average forward current	Single	$I_{F(AV)}$	mA
	Double*1	225	
Average forward current	Single	$I_{F(AV)}$	mA
	Double*1	150	
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Note) *1 : Value per chip

*2 : The peak-to-peak value in one cycle of 50 Hz sine-wave (non-repetitive)

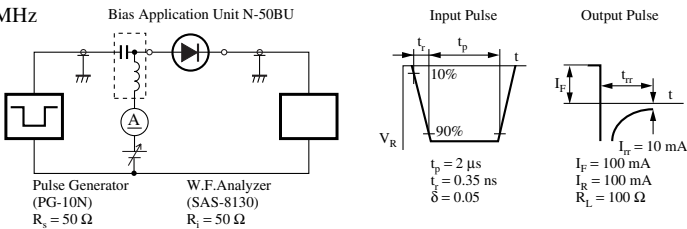
■ Electrical Characteristics $T_a = 25^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse current (DC)	I_R	$V_R = 50 \text{ V}$			200	μA
Forward voltage (DC)	V_{F1}	$I_F = 30 \text{ mA}$			0.36	V
	V_{F2}	$I_F = 200 \text{ mA}$			0.55	V
Terminal capacitance	C_t	$V_R = 0 \text{ V}, f = 1 \text{ MHz}$		30		pF
Reverse recovery time*	t_{rr}	$I_F = I_R = 100 \text{ mA}$ $I_{rr} = 10 \text{ mA}, R_L = 100 \Omega$		3.0		ns

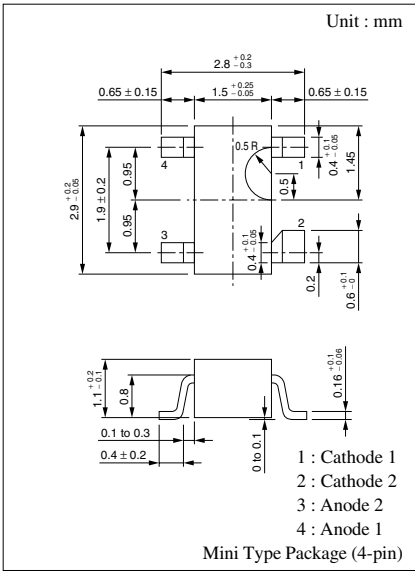
Note) 1. Schottky barrier diode is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

2. Rated input/output frequency: 2 000 MHz

3. *: t_{rr} measuring instrument

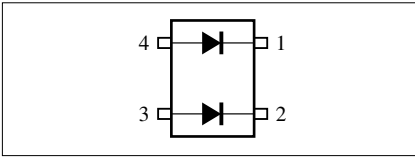


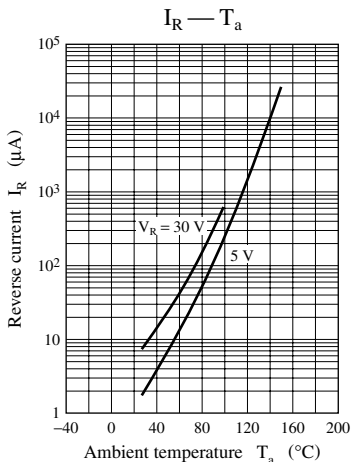
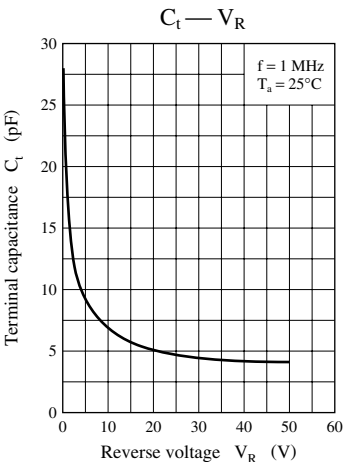
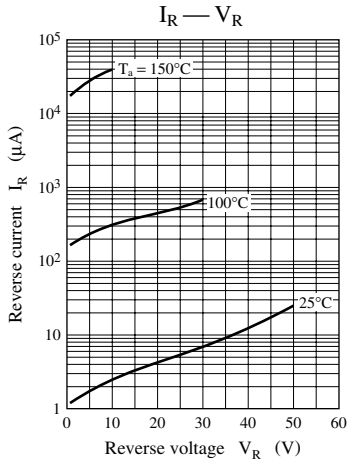
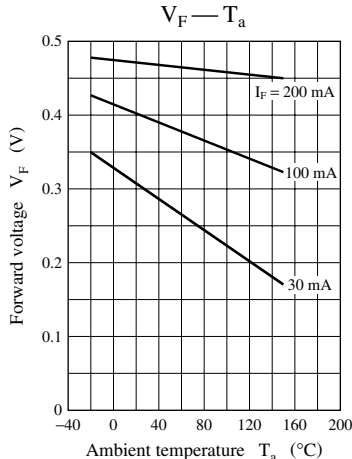
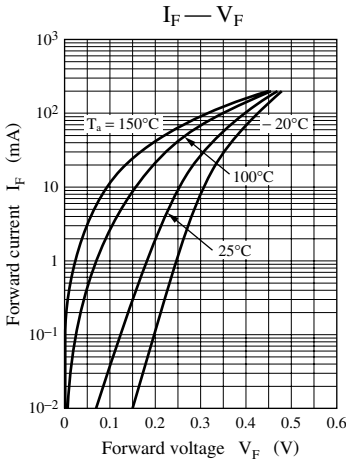
Note) The part number in the parenthesis shows conventional part number.



Marking Symbol: M3M

Internal Connection





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